



## 3.3-V AND/OR 5-V HIGH-SPEED DIGITAL ISOLATORS

Check for Samples: [ISO721-Q1](#), [ISO722-Q1](#)

### FEATURES

- Qualified for Automotive Applications
- AEC-Q100 Qualified With the Following Results:
  - Device Temperature Grade 1: –40°C to 125°C Ambient Operating Temperature Range
  - Device HBM ESD Classification Level H2
  - Device CDM ESD Classification Level C5
- 4000-V<sub>(peak)</sub> Isolation
  - UL 1577, IEC 60747-5-2 (VDE 0884, Rev 2), IEC 61010-1
  - 50-kV/s Transient Immunity (Typ)
- Signaling Rate 0 Mbps to 100 Mbps
  - Low Propagation Delay
  - Low Pulse Skew (Pulse-Width Distortion)
- Low-Power Sleep Mode
- High Electromagnetic Immunity
- Low Input Current Requirement
- Failsafe Output
- Drop-In Replacement for Most Optical and Magnetic Isolators

### DESCRIPTION

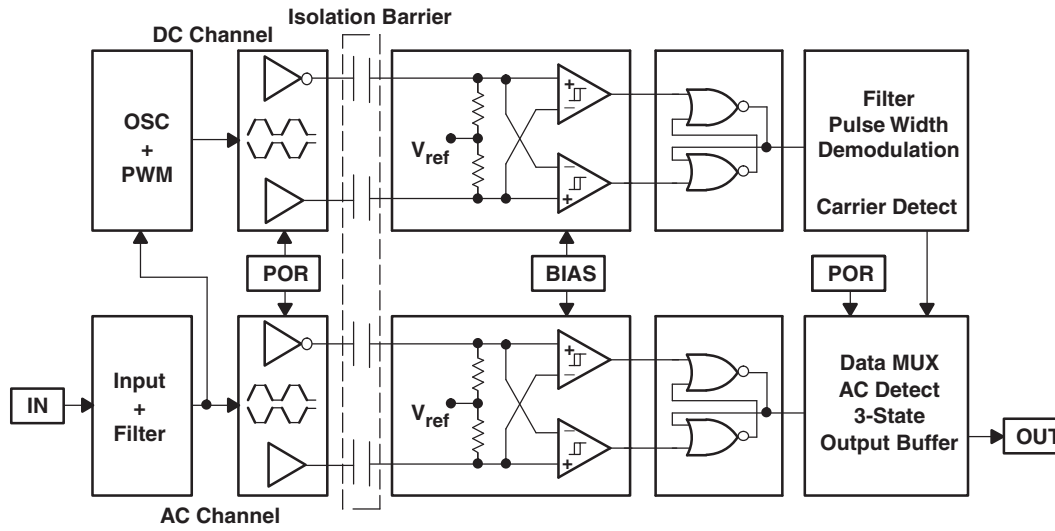
The ISO72x-Q1 is a digital isolator with a logic input and output buffer separated by a silicon oxide (SiO<sub>2</sub>) insulation barrier. This barrier provides galvanic isolation of up to 4000 V. Used in conjunction with isolated power supplies, this device prevents noise currents on a data bus or other circuits from entering the local ground and interfering with or damaging sensitive circuitry.

The capacitive isolation barrier conditions, translates to a balanced signal, then differentiates a binary input signal. Across the isolation barrier, a differential comparator receives the logic-transition information, then sets or resets a flip-flop and the output circuit accordingly. A periodic update pulse sent across the barrier ensures the proper dc level of the output. On failure to receive this dc refresh pulse for more than 4 μs, the response of the device is as if the input is or not actively driven, and the failsafe circuit drives the output to a logic-high state.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

FUNCTION DIAGRAM



## DESCRIPTION (CONTINUED)

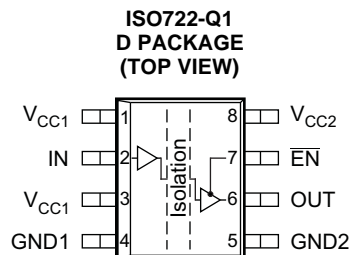
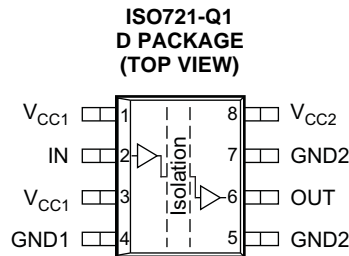
The symmetry of the dielectric and capacitor within the integrated circuitry provides for close capacitive matching and allows fast transient voltage changes between the input and output grounds without corrupting the output. The small capacitance and resulting time constant provide for fast operation with signaling rates<sup>(1)</sup> from 0 Mbps (dc) to 100 Mbps.

The device requires two supply voltages of 3.3 V, 5 V, or any combination. All inputs are 5-V tolerant when supplied from a 3.3-V supply, and all outputs are 4-mA CMOS. The device has a TTL input threshold and a noise filter at the input that prevents transient pulses of up to 2 ns in duration from being passed to the output of the device.

The ISO722-Q1 device includes an active-low output enable that, when driven to a high logic level, places the output in a high-impedance state and turns off internal bias circuitry to conserve power.

The ISO72x-Q1 is characterized for operation over the ambient temperature range of –40°C to 125°C.

(1) The signaling rate of a line is the number of voltage transitions that occur per second, expressed in the units bps (bits per second).



## ORDERING AND PACKAGING INFORMATION

For the most-current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at [www.ti.com](http://www.ti.com).

Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

**Table 1. REGULATORY INFORMATION**

VDE	CSA	UL
Certified according to IEC 60747-5-2	Approved under CSA Component Acceptance Notice: CA-5A	Recognized under 1577 Component Recognition Program <sup>(1)</sup>
File Number: 40016131	File Number: 1698195	File Number: E181974

(1) Production tested  $\geq 3000 V_{RMS}$  for 1 second in accordance with UL 1577.

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

V <sub>CC</sub>	Supply voltage <sup>(2)</sup> , V <sub>CC1</sub> , V <sub>CC2</sub>		-0.5 V to 6 V
V <sub>I</sub>	Voltage at IN or OUT terminal		-0.5 V to 6 V
I <sub>O</sub>	Output current		±15 mA
T <sub>J</sub>	Maximum virtual-junction temperature		170°C
ESD	Electrostatic discharge rating	Human-Body Model <sup>(3)</sup>	±2 kV
		Charged-Device Model <sup>(4)</sup>	±1 kV

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values except differential I/O bus voltages are with respect to network ground terminal and are peak voltage values. Vrms values are not listed in this publication.
- (3) JEDEC Standard 22, Test Method A114-C.01
- (4) JEDEC Standard 22, Test Method C101

**RECOMMENDED OPERATING CONDITIONS**

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage <sup>(1)</sup> , V <sub>CC1</sub> , V <sub>CC2</sub>	3	5.5	V
I <sub>OH</sub>	High-level output current		4	mA
I <sub>OL</sub>	Low-level output current	-4		mA
t <sub>ui</sub>	Input pulse duration	10		ns
V <sub>IH</sub>	High-level input voltage (IN)	2	V <sub>CC</sub>	V
V <sub>IL</sub>	Low-level input voltage (IN)	0	0.8	V
T <sub>A</sub>	Operating free-air temperature	-40	125	°C
T <sub>J</sub>	Operating virtual-junction temperature	See the Thermal Characteristics table		150 °C
H	External magnetic field intensity per IEC 61000-4-8 and IEC 61000-4-9 certification		1000	A/m

- (1) For 5-V operation, V<sub>CC1</sub> or V<sub>CC2</sub> specification is from 4.5 V to 5.5 V. For 3.3-V operation, V<sub>CC1</sub> or V<sub>CC2</sub> specification is from 3 V to 3.6 V.

**IEC 60747-5-2 INSULATION CHARACTERISTICS<sup>(1)</sup>**

over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SPECIFICATIONS	UNIT
V <sub>IORM</sub>	Maximum working insulation voltage	560	V
V <sub>PR</sub>	Input-to-output test voltage	After Input/Output Safety Test Subgroup 2/3 V <sub>PR</sub> = V <sub>IORM</sub> × 1.2, t = 10 s, Partial discharge < 5 pC	672 V
		Method a, V <sub>PR</sub> = V <sub>IORM</sub> × 1.6, Type and sample test with t = 10 s, Partial discharge < 5 pC	896 V
		Method b1, V <sub>PR</sub> = V <sub>IORM</sub> × 1.875, 100 % Production test with t = 1 s, Partial discharge < 5 pC	1050 V
V <sub>IOTM</sub>	Transient overvoltage	t = 60 s	4000 V
R <sub>S</sub>	Insulation resistance	V <sub>IO</sub> = 500 V at T <sub>S</sub>	>10 <sup>9</sup> Ω
	Pollution degree		2

- (1) Climatic Classification 40/125/21

**ELECTRICAL CHARACTERISTICS:  $V_{CC1}$  and  $V_{CC2}$  5-V<sup>(1)</sup> OPERATION**

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$I_{CC1}$	$V_{CC1}$ supply current	Quiescent	$V_I = V_{CC}$ or 0 V, No load		0.5	1	mA
		25 Mbps			2	4	
$I_{CC2}$	$V_{CC2}$ supply current	ISO722-Q1 Sleep Mode	$V_I = V_{CC}$ or 0 V, No load			200	$\mu$ A
		Quiescent				$\overline{EN}$ at $V_{CC}$	
		25 Mbps	$V_I = V_{CC}$ or 0 V, No load		8	12	mA
$V_{OH}$	High-level output voltage		$I_{OH} = -4$ mA, See <a href="#">Figure 1</a>		$V_{CC} - 0.8$	4.6	
			$I_{OH} = -20$ $\mu$ A, See <a href="#">Figure 1</a>		$V_{CC} - 0.1$	5	
$V_{OL}$	Low-level output voltage		$I_{OL} = 4$ mA, See <a href="#">Figure 1</a>		0.2	0.4	V
			$I_{OL} = 20$ $\mu$ A, See <a href="#">Figure 1</a>		0	0.1	
$V_{I(HYS)}$	Input voltage hysteresis				150		mV
$I_{IH}$	High-level input current		IN at 2 V			10	$\mu$ A
$I_{IL}$	Low-level input current		IN at 0.8 V		-10		
$I_{OZ}$	High-impedance output current	ISO722-Q1	$\overline{EN}$ , IN at $V_{CC}$			1	$\mu$ A
$C_1$	Input capacitance to ground		IN at $V_{CC}$ , $V_I = 0.4 \sin(4E6\pi t)$		1		pF
CMTI	Common-mode transient immunity		$V_I = V_{CC}$ or 0 V, See <a href="#">Figure 5</a>		15	50	kV/ $\mu$ s

 (1) For 5-V operation,  $V_{CC1}$  or  $V_{CC2}$  specification is from 4.5 V to 5.5 V. For 3.3-V operation,  $V_{CC1}$  or  $V_{CC2}$  specification is from 3 V to 3.6 V.

**SWITCHING CHARACTERISTICS:  $V_{CC1}$  and  $V_{CC2}$  5-V OPERATION**

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
$t_{PLH}$	Propagation delay, low-to-high-level output		See <a href="#">Figure 1</a>		17	24	ns	
$t_{PHL}$	Propagation delay, high-to-low-level output		See <a href="#">Figure 1</a>		17	24	ns	
$t_{sk(p)}$	Pulse skew $ t_{PHL} - t_{PLH} $		See <a href="#">Figure 1</a>		0.5	2	ns	
$t_{sk(PP)}$	Part-to-part skew				0	3	ns	
$t_r$	Output-signal rise time		See <a href="#">Figure 1</a>		1		ns	
$t_f$	Output-signal fall time		See <a href="#">Figure 1</a>		1		ns	
$t_{pHZ}$	Sleep-mode propagation delay, high-level-to-high-impedance output	ISO722-Q1	See <a href="#">Figure 2</a>		6	8	15	ns
$t_{pZH}$	Sleep-mode propagation delay, high-impedance-to-high-level output				3.5	4	8	$\mu$ s
$t_{pLZ}$	Sleep-mode propagation delay, low-level-to-high-impedance output				5.5	8	15	ns
$t_{pZL}$	Sleep-mode propagation delay, high-impedance-to-low-level output				See <a href="#">Figure 3</a>	4	5	8
$t_{fs}$	Failsafe output delay time from input power loss		See <a href="#">Figure 4</a>		3		$\mu$ s	
$t_{jit(PP)}$	Peak-to-peak eye-pattern jitter		100-Mbps NRZ data input, See <a href="#">Figure 6</a>		2		ns	
			100-Mbps unrestricted bit run length data input, See <a href="#">Figure 6</a>		3			

 (1)  $t_{sk(PP)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

**ELECTRICAL CHARACTERISTICS:  $V_{CC1}$  at 5-V,  $V_{CC2}$  at 3.3-V<sup>(1)</sup> OPERATION**

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
$I_{CC1}$	$V_{CC1}$ supply current	Quiescent	$V_I = V_{CC}$ or 0 V, No load		0.5	1	mA	
		25 Mbps			2	4		
$I_{CC2}$	$V_{CC2}$ supply current	ISO722-Q1	$V_I = V_{CC}$ or 0 V, No load		150		$\mu$ A	
		Quiescent			4 6.5			
		25 Mbps			5 7.5			
$V_{OH}$	High-level output voltage	$I_{OH} = -4$ mA, See <a href="#">Figure 1</a>		$V_{CC} - 0.4$	3		V	
		$I_{OH} = -20$ $\mu$ A, See <a href="#">Figure 1</a>		$V_{CC} - 0.1$	3.3			
$V_{OL}$	Low-level output voltage	$I_{OL} = 4$ mA, See <a href="#">Figure 1</a>		0.2		0.4	V	
		$I_{OL} = 20$ $\mu$ A, See <a href="#">Figure 1</a>		0		0.1		
$V_{I(HYS)}$	Input voltage hysteresis			150			mV	
$I_{IH}$	High-level input current	IN at 2 V				10	$\mu$ A	
$I_{IL}$	Low-level input current	IN at 0.8 V		-10			$\mu$ A	
$I_{OZ}$	High-impedance output current	ISO722-Q1	$\overline{EN}$ , IN at $V_{CC}$				1	$\mu$ A
$C_1$	Input capacitance to ground	IN at $V_{CC}$ , $V_I = 0.4 \sin(4E6\pi t)$				1	pF	
CMTI	Common-mode transient immunity	$V_I = V_{CC}$ or 0 V, See <a href="#">Figure 5</a>		15	40		kV/ $\mu$ s	

(1) For 5-V operation,  $V_{CC1}$  or  $V_{CC2}$  specification is from 4.5 V to 5.5 V. For 3.3-V operation,  $V_{CC1}$  or  $V_{CC2}$  specification is from 3 V to 3.6 V.

**SWITCHING CHARACTERISTICS:  $V_{CC1}$  at 5-V,  $V_{CC2}$  at 3.3-V OPERATION**

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{PLH}$	Propagation delay, low-to-high-level output	See <a href="#">Figure 1</a>			19	30	ns
$t_{PHL}$	Propagation delay, high-to-low-level output	See <a href="#">Figure 1</a>			19	30	ns
$t_{sk(p)}$	Pulse skew $ t_{PHL} - t_{PLH} $	See <a href="#">Figure 1</a>			0.5	3	ns
$t_{sk(PP)}$	Part-to-part skew				0	5	ns
$t_r$	Output signal rise time	See <a href="#">Figure 1</a>			2		ns
$t_f$	Output signal fall time	See <a href="#">Figure 1</a>			2		ns
$t_{pHZ}$	Sleep-mode propagation delay, high-level-to-high-impedance output	ISO722-Q1	See <a href="#">Figure 2</a>	7	13	25	ns
$t_{pZH}$	Sleep-mode propagation delay, high-impedance-to-high-level output			5	6	8	$\mu$ s
$t_{pLZ}$	Sleep-mode propagation delay, low-level-to-high-impedance output		See <a href="#">Figure 3</a>	7	13	25	ns
$t_{pZL}$	Sleep-mode propagation delay, high-impedance-to-low-level output			5	6	8	$\mu$ s
$t_{fs}$	Failsafe output delay time from input power loss	See <a href="#">Figure 4</a>			3		$\mu$ s
$t_{jit(PP)}$	Peak-to-peak eye-pattern jitter	100-Mbps NRZ data input, See <a href="#">Figure 6</a>			2		ns
		100-Mbps unrestricted bit run length data input, See <a href="#">Figure 6</a>			3		

(1)  $t_{sk(PP)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

**ELECTRICAL CHARACTERISTICS:  $V_{CC1}$  at 3.3-V,  $V_{CC2}$  at 5-V<sup>(1)</sup> OPERATION**

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$I_{CC1}$	$V_{CC1}$ supply current	Quiescent	$V_I = V_{CC}$ or 0 V, No load		0.3	0.5	mA
		25 Mbps			1	2	
$I_{CC2}$	$V_{CC2}$ supply current	ISO722-Q1 Sleep Mode	$V_I = V_{CC}$ or 0 V, No load			200	$\mu$ A
		Quiescent		$\overline{EN}$ at 0 V or ISO721-Q1		8	
		25 Mbps	$V_I = V_{CC}$ or 0 V, No load		10	14	
$V_{OH}$	High-level output voltage		$I_{OH} = -4$ mA, See <a href="#">Figure 1</a>	$V_{CC} - 0.8$	4.6		V
			$I_{OH} = -20$ $\mu$ A, See <a href="#">Figure 1</a>	$V_{CC} - 0.1$	5		
$V_{OL}$	Low-level output voltage		$I_{OL} = 4$ mA, See <a href="#">Figure 1</a>		0.2	0.4	V
			$I_{OL} = 20$ $\mu$ A, See <a href="#">Figure 1</a>		0	0.1	
$V_{I(HYS)}$	Input voltage hysteresis				150		mV
$I_{IH}$	High-level input current		IN at 2 V			10	$\mu$ A
$I_{IL}$	Low-level input current		IN at 0.8 V		-10		$\mu$ A
$I_{OZ}$	High-impedance output current	ISO722-Q1	$\overline{EN}$ , IN at $V_{CC}$			1	$\mu$ A
$C_1$	Input capacitance to ground		IN at $V_{CC}$ , $V_I = 0.4 \sin(4E6\pi t)$		1		pF
CMTI	Common-mode transient immunity		$V_I = V_{CC}$ or 0 V, See <a href="#">Figure 5</a>		15	40	kV/ $\mu$ s

 (1) For 5-V operation,  $V_{CC1}$  or  $V_{CC2}$  specification is from 4.5 V to 5.5 V. For 3.3-V operation,  $V_{CC1}$  or  $V_{CC2}$  specification is from 3 V to 3.6 V.

**SWITCHING CHARACTERISTICS:  $V_{CC1}$  at 3.3-V,  $V_{CC2}$  at 5-V OPERATION**

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT		
$t_{PLH}$	Propagation delay, low-to-high-level output		See <a href="#">Figure 1</a>		17	30	ns		
$t_{PHL}$	Propagation delay, high-to-low-level output		See <a href="#">Figure 1</a>		17	30	ns		
$t_{sk(p)}$	Pulse skew $ t_{PHL} - t_{PLH} $		See <a href="#">Figure 1</a>		0.5	3	ns		
$t_{sk(pp)}$	Part-to-part skew				0	5	ns		
$t_r$	Output signal rise time		See <a href="#">Figure 1</a>		2		ns		
$t_f$	Output signal fall time		See <a href="#">Figure 1</a>		2		ns		
$t_{pHZ}$	Sleep-mode propagation delay, high-level-to-high-impedance output	ISO722-Q1	See <a href="#">Figure 2</a>		7	9	15	ns	
$t_{pZH}$	Sleep-mode propagation delay, high-impedance-to-high-level output				4.5	5	8	$\mu$ s	
$t_{pLZ}$	Sleep-mode propagation delay, low-level-to-high-impedance output			See <a href="#">Figure 3</a>		7	9	15	ns
$t_{pZL}$	Sleep-mode propagation delay, high-impedance-to-low-level output					4.5	5	8	$\mu$ s
$t_{fs}$	Failsafe output delay time from input power loss		See <a href="#">Figure 4</a>		3		$\mu$ s		
$t_{jit(pp)}$	Peak-to-peak eye-pattern jitter		100-Mbps NRZ data input, See <a href="#">Figure 6</a>		2		ns		
			100-Mbps unrestricted bit run length data input, See <a href="#">Figure 6</a>		3				

 (1)  $t_{sk(pp)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

### ELECTRICAL CHARACTERISTICS: $V_{CC1}$ and $V_{CC2}$ at 3.3-V<sup>(1)</sup> OPERATION

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$I_{CC1}$	$V_{CC1}$ supply current	Quiescent	$V_I = V_{CC}$ or 0 V, No load		0.3	0.5	mA
		25 Mbps			1	2	
$I_{CC2}$	$V_{CC2}$ supply current	ISO722-Q1 Sleep Mode	$V_I = V_{CC}$ or 0 V, No load			150	$\mu$ A
		Quiescent		$\overline{EN}$ at $V_{CC}$		4	
		25 Mbps	$V_I = V_{CC}$ or 0 V, No load	$\overline{EN}$ at 0 V or ISO721-Q1		5	7.5
$V_{OH}$	High-level output voltage		$I_{OH} = -4$ mA, See <a href="#">Figure 1</a>	$V_{CC} - 0.4$	3		V
			$I_{OH} = -20$ $\mu$ A, See <a href="#">Figure 1</a>	$V_{CC} - 0.1$	3.3		
$V_{OL}$	Low-level output voltage		$I_{OL} = 4$ mA, See <a href="#">Figure 1</a>		0.2	0.4	V
			$I_{OL} = 20$ $\mu$ A, See <a href="#">Figure 1</a>		0	0.1	
$V_{I(HYS)}$	Input voltage hysteresis				150		mV
$I_{IH}$	High-level input current		IN at 2 V			10	$\mu$ A
$I_{IL}$	Low-level input current		IN at 0.8 V		-10		$\mu$ A
$I_{OZ}$	High-impedance output current	ISO722-Q1	$\overline{EN}$ , IN at $V_{CC}$			1	$\mu$ A
$C_1$	Input capacitance to ground		IN at $V_{CC}$ , $V_I = 0.4 \sin(4E6\pi t)$		1		pF
CMTI	Common-mode transient immunity		$V_I = V_{CC}$ or 0 V, See <a href="#">Figure 5</a>		15	40	kV/ $\mu$ s

(1) For 5-V operation,  $V_{CC1}$  or  $V_{CC2}$  specification is from 4.5 V to 5.5 V. For 3.3-V operation,  $V_{CC1}$  or  $V_{CC2}$  specification is from 3 V to 3.6 V.

### SWITCHING CHARACTERISTICS: $V_{CC1}$ and $V_{CC2}$ at 3.3-V OPERATION

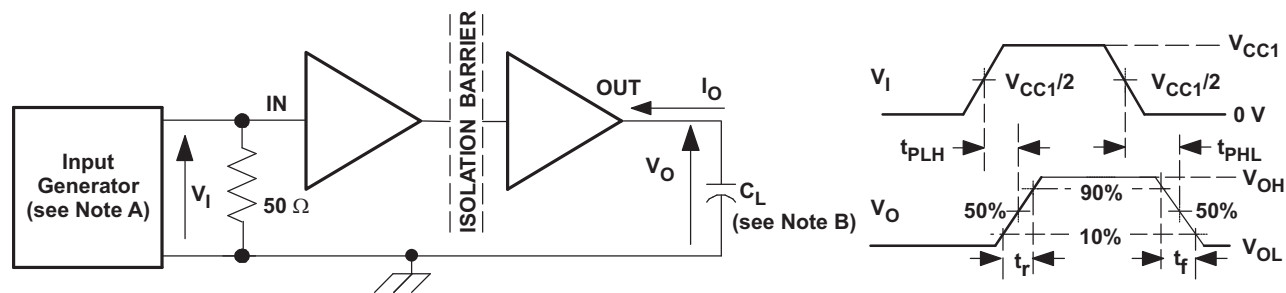
over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT		
$t_{PLH}$	Propagation delay, low-to-high-level output		See <a href="#">Figure 1</a>		20	34	ns		
$t_{PHL}$	Propagation delay, high-to-low-level output		See <a href="#">Figure 1</a>		20	34	ns		
$t_{sk(p)}$	Pulse skew $ t_{PHL} - t_{PLH} $		See <a href="#">Figure 1</a>		0.5	3	ns		
$t_{sk(pp)}$	Part-to-part skew				0	5	ns		
$t_r$	Output signal rise time		See <a href="#">Figure 1</a>		2		ns		
$t_f$	Output signal fall time		See <a href="#">Figure 1</a>		2		ns		
$t_{pHZ}$	Sleep-mode propagation delay, high-level-to-high-impedance output	ISO722-Q1	See <a href="#">Figure 2</a>		7	13	25	ns	
$t_{pZH}$	Sleep-mode propagation delay, high-impedance-to-high-level output				5	6	8	$\mu$ s	
$t_{pLZ}$	Sleep-mode propagation delay, low-level-to-high-impedance output			See <a href="#">Figure 3</a>		7	13	25	ns
$t_{pZL}$	Sleep-mode propagation delay, high-impedance-to-low-level output					5	6	8	$\mu$ s
$t_{fs}$	Failsafe output delay time from input power loss		See <a href="#">Figure 4</a>		3		$\mu$ s		
$t_{jit(pp)}$	Peak-to-peak eye-pattern jitter		100-Mbps NRZ data input, See <a href="#">Figure 6</a>		2		ns		
			100-Mbps unrestricted bit run length data input, See <a href="#">Figure 6</a>		3				

(1)  $t_{sk(pp)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.



PARAMETER MEASUREMENT INFORMATION



- A. A generator having the following characteristics supplies the input pulse:  
 $PRR \leq 50 \text{ kHz}$ , 50% duty cycle,  $t_r \leq 3 \text{ ns}$ ,  $t_f \leq 3 \text{ ns}$ ,  $Z_O = 50 \Omega$ .
- B.  $C_L = 15 \text{ pF}$  and includes instrumentation and fixture capacitance within  $\pm 20\%$ .

Figure 1. Switching Characteristic Test Circuit and Voltage Waveforms

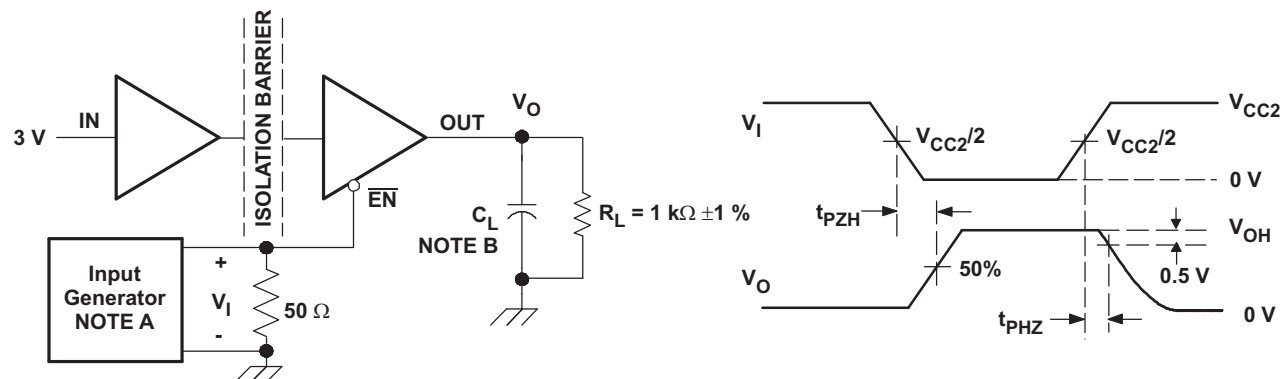


Figure 2. ISO722-Q1 Sleep-Mode High-Level Output Test Circuit and Voltage Waveforms

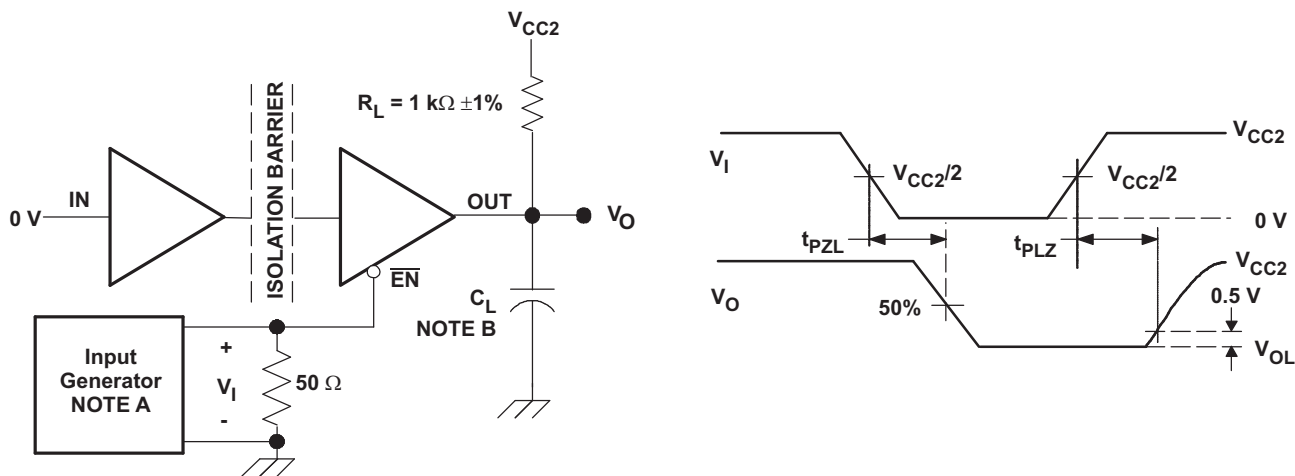
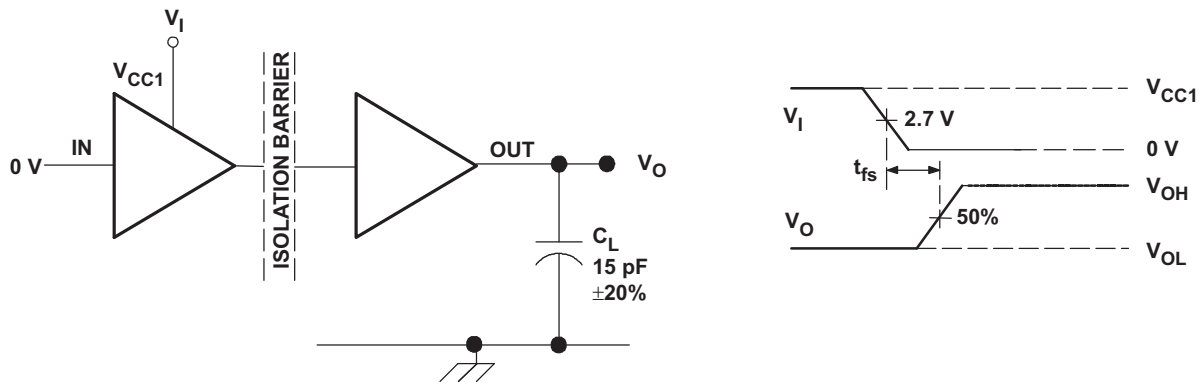


Figure 3. ISO722-Q1 Sleep-Mode Low-Level Output Test Circuit and Voltage Waveforms

NOTE

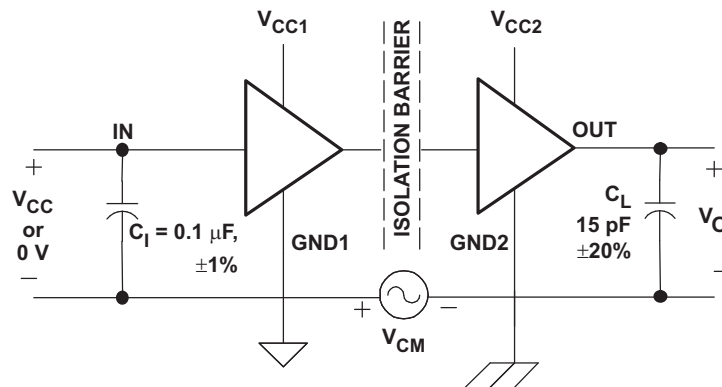
- A: A generator having the following characteristics Supplies the input pulse:  
 $PRR \leq 50 \text{ kHz}$ , 50% duty cycle,  $t_r \leq 3 \text{ ns}$ ,  $t_f \leq 3 \text{ ns}$ ,  $Z_O = 50 \Omega$ .
- B:  $C_L = 15 \text{ pF} \pm 20\%$  and includes instrumentation and fixture capacitance.

PARAMETER MEASUREMENT INFORMATION (continued)



NOTE:  $V_I$  transition time is 100 ns.

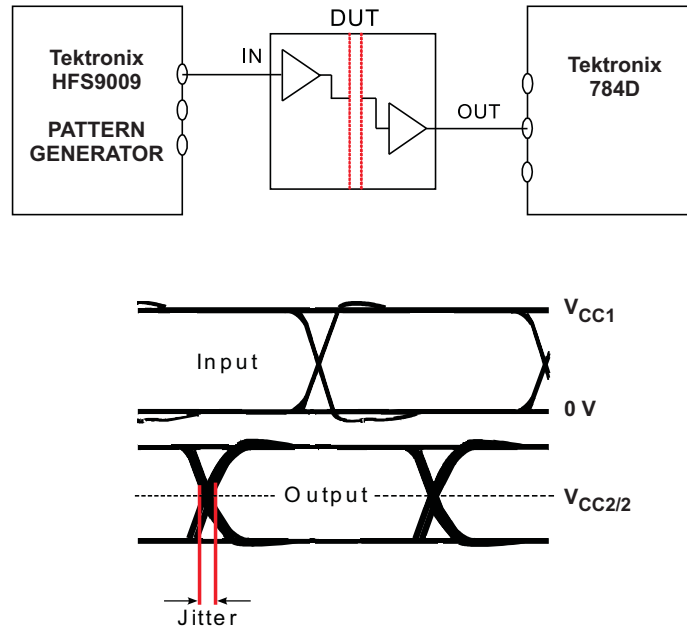
Figure 4. Failsafe Delay-Time Test Circuit and Voltage Waveforms



NOTE: Pass or fail criterion is no change in  $V_O$ .

Figure 5. Common-Mode Transient Immunity Test Circuit and Voltage Waveform

PARAMETER MEASUREMENT INFORMATION (continued)



NOTE: Bit pattern run length is  $2^{16} - 1$ . Transition time is 800 ps. NRZ data input has no more than five consecutive 1s or 0s.

Figure 6. Peak-to-Peak Eye-Pattern Jitter Test Circuit and Voltage Waveform

**DEVICE INFORMATION**

**PACKAGE CHARACTERISTICS**

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
L(101)	Minimum air gap (clearance) <sup>(1)</sup>	Shortest terminal-to-terminal distance through air			4.8	mm
L(102)	Minimum external tracking (creepage)	Shortest terminal-to-terminal distance across the package surface			4.3	mm
C <sub>TI</sub>	Tracking resistance (comparative tracking index)	DIN IEC 60112/VDE 0303 Part 1			≥ 175	V
	Minimum internal gap (internal clearance)	Distance through insulation			0.008	mm
R <sub>IO</sub>	Isolation resistance	Input to output, V <sub>IO</sub> = 500 V, all pins on each side of the barrier tied together creating a two-terminal device, T <sub>A</sub> < 100°C			>10 <sup>12</sup>	Ω
		Input-to-output, V <sub>IO</sub> = 500 V, 100°C ≤ T <sub>A</sub> < T <sub>A</sub> max.			>10 <sup>11</sup>	Ω
C <sub>IO</sub>	Barrier capacitance, input to output	V <sub>I</sub> = 0.4 sin (4E6πt)			1	pF
C <sub>I</sub>	Input capacitance to ground	V <sub>I</sub> = 0.4 sin (4E6πt)			1	pF

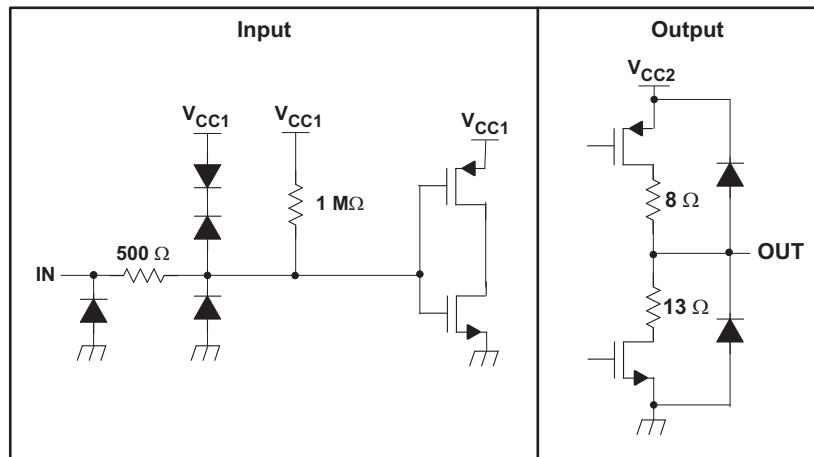
- (1) Apply creepage and clearance requirements according to the specific equipment isolation standards of an application. Take care to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed circuit board do not reduce this distance.  
 Creepage and clearance on a printed circuit board become equal according to the measurement techniques shown in the Isolation Glossary. Use techniques such as inserting grooves and/or ribs on a printed circuit board to help increase these specifications.

**IEC 60664-1 RATINGS TABLE**

PARAMETER	TEST CONDITIONS	SPECIFICATION
Basic isolation group	Material group	IIIa
Installation classification	Rated mains voltage ≤150 VRMS	I-IV
	Rated mains voltage ≤300 VRMS	I-III

**DEVICE I/O SCHEMATIC**

**Figure 7. Equivalent Input and Output Schematic Diagrams**



**IEC SAFETY LIMITING VALUES**

Safety limiting is designed to prevent potential damage to the isolation barrier on failure of input or output circuitry. A failure of the IO can allow low resistance to ground or the supply, and without current limiting, dissipate sufficient power to overheat the die and damage the isolation barrier, potentially leading to secondary system failures.

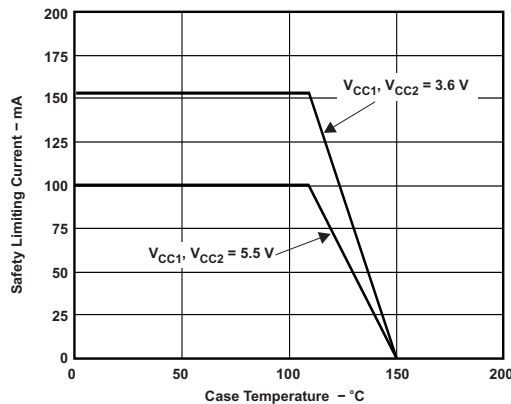
PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
I <sub>S</sub>	Safety input, output, or supply current	θ <sub>JA</sub> = 263°C/W, V <sub>I</sub> = 5.5 V, T <sub>J</sub> = 170°C, T <sub>A</sub> = 25°C		100	mA
		θ <sub>JA</sub> = 263°C/W, V <sub>I</sub> = 3.6 V, T <sub>J</sub> = 170°C, T <sub>A</sub> = 25°C		153	
T <sub>S</sub>	Maximum case temperature			150	°C

The safety-limiting constraint is the absolute maximum junction temperature specified in the absolute maximum ratings table. The power dissipation and junction-to-air thermal impedance of the device installed in the application hardware determines the junction temperature. The junction-to-air thermal resistance in the Thermal Characteristics table is that of a device installed in the JESD51-3, Low Effective Thermal Conductivity Test Board for Leaded Surface Mount Packages and is conservative. The power is the recommended maximum input voltage times the current. The junction temperature is then the ambient temperature plus the power times the junction-to-air thermal resistance.

**Table 2. THERMAL CHARACTERISTICS**  
(over recommended operating conditions unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
θ <sub>JA</sub>	Junction-to-air thermal resistance	Low-K <sup>(1)</sup>		263		°C/W
		High-K <sup>(1)</sup>		125		
θ <sub>JB</sub>	Junction-to-board thermal resistance			44		°C/W
θ <sub>JC</sub>	Junction-to-case thermal resistance			75		°C/W
P <sub>D</sub>	Device power dissipation	V <sub>CC1</sub> = V <sub>CC2</sub> = 5.5 V, T <sub>J</sub> = 150°C, C <sub>L</sub> = 15 pF, Input a 100-Mbps 50% duty cycle square wave			159	mW

(1) Tested in accordance with the low-K or high-K thermal metric definition of EIA/JESD51-3 for leaded surface-mount packages.



**Figure 8. θ<sub>JC</sub> Thermal Derating Curve Per IEC 60747-5-2**

**Table 3. FUNCTION TABLE<sup>(1)</sup>**

$V_{CC1}$	$V_{CC2}$	INPUT (IN)	OUTPUT (OUT)
PU	PU	H	H
		L	L
		Open	H
PD	PU	X	H

(1) PU = powered up ( $V_{CC} \geq 3\text{ V}$ ), PD = powered down ( $V_{CC} \leq 2.5\text{ V}$ ), X = irrelevant, H = high level, L = low level

TYPICAL CHARACTERISTICS

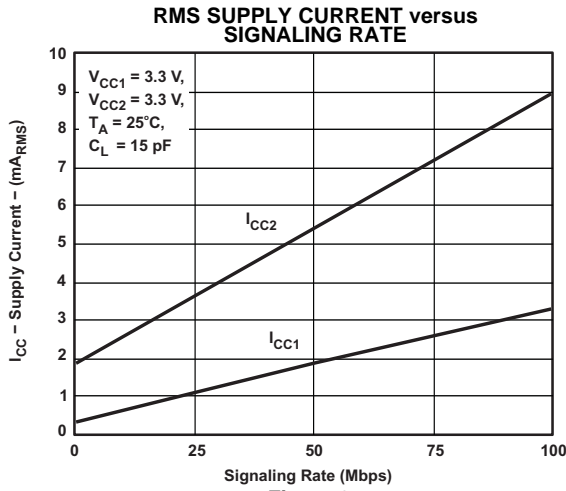


Figure 9.

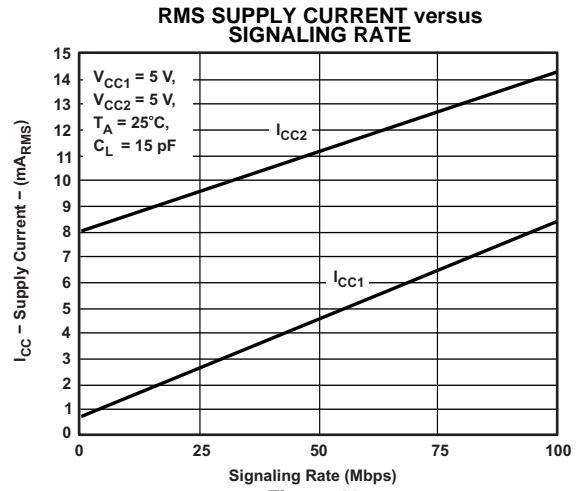


Figure 10.

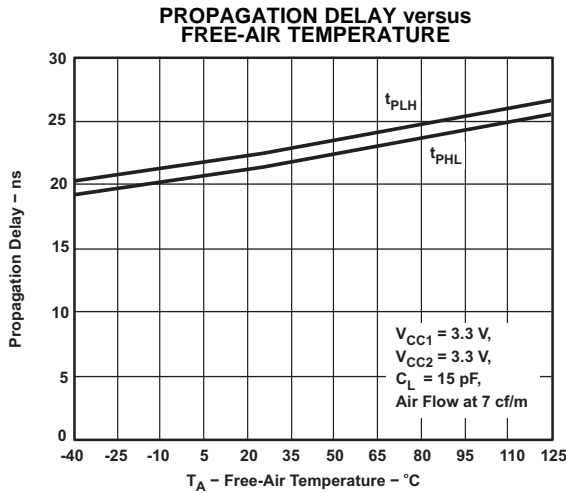


Figure 11.

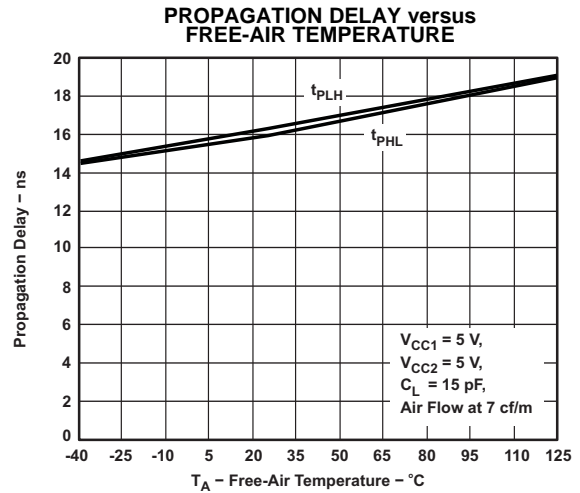


Figure 12.

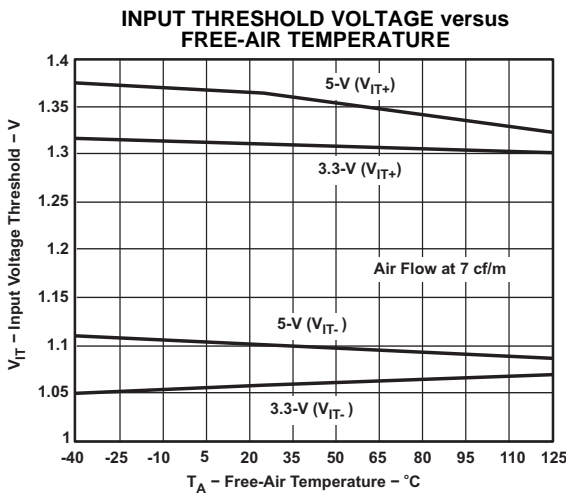


Figure 13.

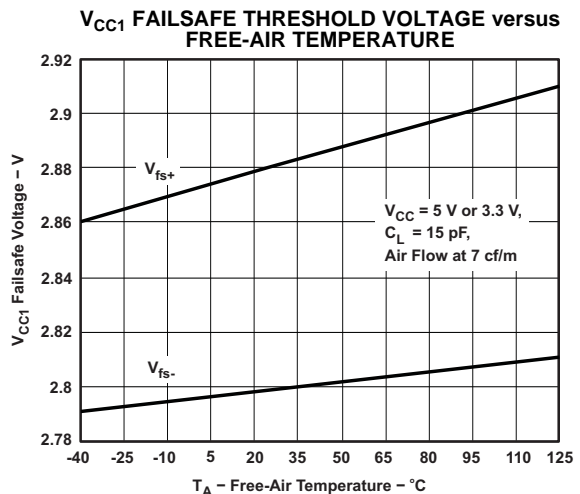
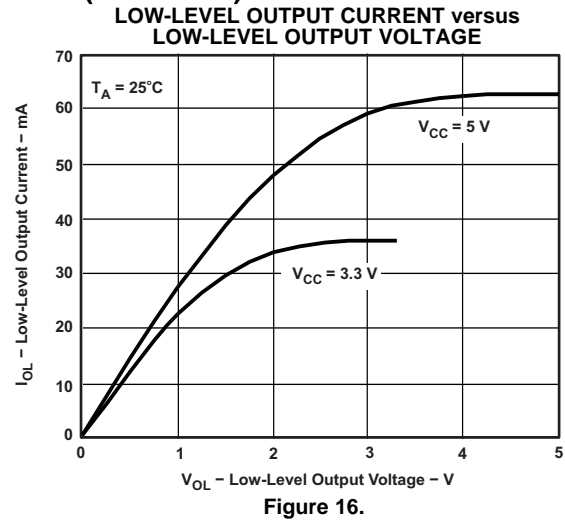
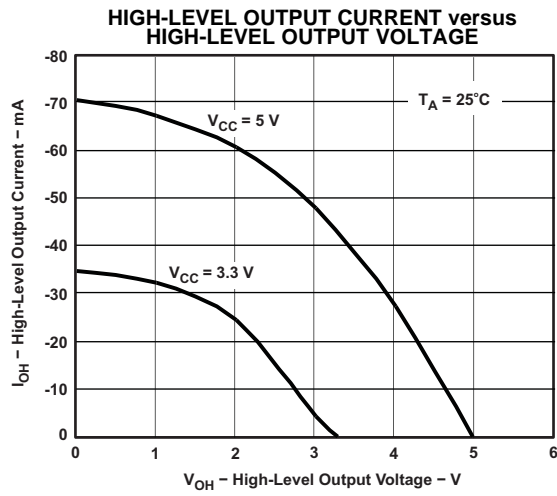


Figure 14.

**TYPICAL CHARACTERISTICS (continued)**





APPLICATION INFORMATION

MANUFACTURER CROSS-REFERENCE DATA

The ISO72x-Q1 isolator has the same functional pinout as most other vendors, and it is often a pin-for-pin drop-in replacement. The notable differences in the product are propagation delay, signaling rate, power consumption, and transient protection rating. Use <sup>(1)</sup> as a guide for replacing other isolators with the ISO72x-Q1 single-channel isolators.

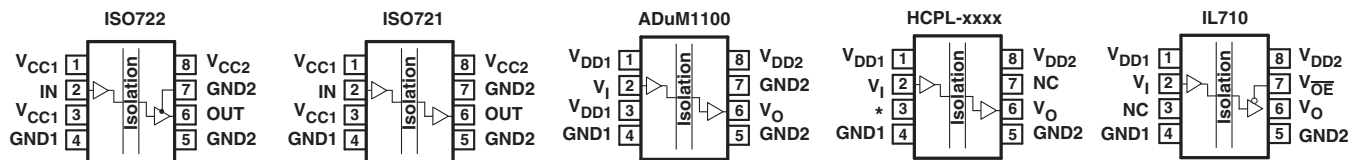


Figure 17. Pinout Cross-Reference

Table 4. Competitive Cross-Reference

ISOLATOR	PIN 1	PIN 2	PIN 3	PIN 4	PIN 5	PIN 6	PIN 7		PIN 8
							ISO721	ISO722	
ISO721 <sup>(1) (2)</sup>	V <sub>CC1</sub>	IN	V <sub>CC1</sub>	GND1	GND2	OUT	GND2	$\overline{\text{EN}}$	V <sub>CC2</sub>
ADuM1100 <sup>(1) (2)</sup>	V <sub>DD1</sub>	V <sub>I</sub>	V <sub>DD1</sub>	GND1	GND2	V <sub>O</sub>	GND2		V <sub>DD2</sub>
HCPL-xxxx	V <sub>DD1</sub>	V <sub>I</sub>	Leave open <sup>(3)</sup>	GND1	GND2	V <sub>O</sub>	NC <sup>(4)</sup>		V <sub>DD2</sub>
IL710	V <sub>DD1</sub>	V <sub>I</sub>	NC <sup>(5)</sup>	GND1	GND2	V <sub>O</sub>	$\overline{\text{OE}}$		V <sub>DD2</sub>

- (1) An HCPL device pin 7 must be floating (open) or grounded to use an ISO722 device as a drop-in replacement. Placing pin 7 of the ISO722 device in a high logic state disables the output of the device.
- (1) The ISO721 pin 1 and pin 3 connect together internally. One may use either or both as V<sub>CC1</sub>.
- (2) The ISO721 pin 5 and pin 7 connect together internally. One may use either or both as GND2.
- (3) Pin 3 of the HCPL devices must be open. This is not a problem when substituting an ISO721, because the extra V<sub>CC1</sub> on pin 3 may be open-circuit as well.
- (4) An HCPL device pin 7 must be floating (open) or grounded to use an ISO722 device as a drop-in replacement. Placing pin 7 of the ISO722 device in a high logic state disables the output of the device.
- (5) Pin 3 of the IL710 must not tie to ground on the circuit board, because this shorts the ISO721 V<sub>CC1</sub> to ground. The IL710 pin 3 may only tie to V<sub>CC</sub> or be open to drop in an ISO721.

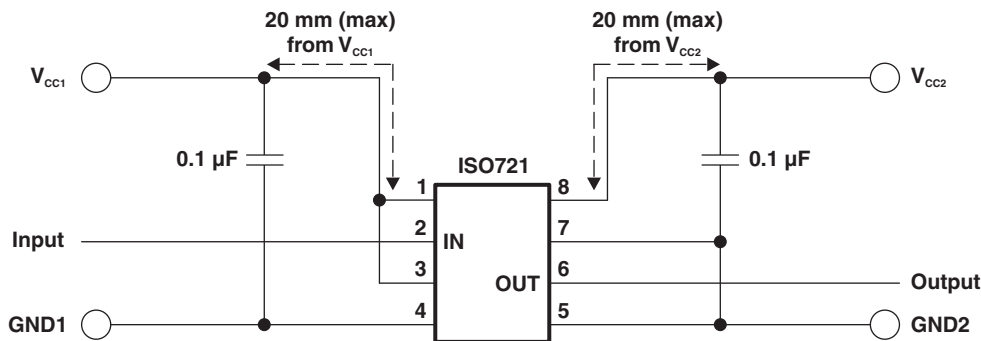
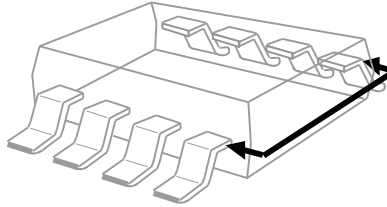


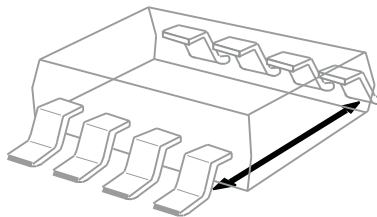
Figure 18. Basic Application Circuit

## ISOLATION GLOSSARY

**Creepage Distance**—The shortest path between two conductive input to output leads measured along the surface of the insulation. The shortest-distance path is around the end of the package body.



**Clearance**—The shortest distance between two conductive input to output leads measured through air (line of sight)



**Input-to-Output Barrier Capacitance**—The total capacitance between all input terminals connected together, and all output terminals connected together

**Input-to-Output Barrier Resistance**—The total resistance between all input terminals connected together, and all output terminals connected together

**Primary Circuit**—An internal circuit directly connected to an external supply main or other equivalent source which supplies the primary-circuit electric power

**Secondary Circuit**—A circuit with no direct connection to primary power, and deriving its power from a separate isolated source

**Comparative Tracking Index (CTI)**—CTI is an index used for electrical insulating materials and defined as the numerical value of the voltage that causes failure by tracking during standard testing. Tracking is the process that produces a partially conducting path of localized deterioration on or through the surface of an insulating material as a result of the action of electric discharges on or close to an insulation surface -- the higher CTI value of the insulating material, the smaller the minimum creepage distance.

Generally, insulation breakdown occurs either through the material, over its surface, or both. Surface failure may arise from flashover or from the progressive degradation of the insulation surface by small localized sparks. Such sparks are the result of the breaking of a surface film of conducting contaminant on the insulation. The resulting break in the leakage current produces an overvoltage at the site of the discontinuity, generating an electric spark. These sparks often cause carbonization on insulation material and lead to a carbon track between points of different potential. The name of this process is *tracking*.

## Insulation

*Operational insulation*—Insulation needed for the correct operation of the equipment

*Basic insulation*—Insulation to provide basic protection against electric shock

*Supplementary insulation*—Independent insulation applied in addition to basic insulation in order to ensure protection against electric shock in the event of a failure of the basic insulation

*Double insulation*—Insulation comprising both basic and supplementary insulation

*Reinforced insulation*—A single insulation system that provides a degree of protection against electric shock equivalent to double insulation

## Pollution Degree

*Pollution Degree 1*—No pollution, or only dry, nonconductive pollution occurs. The pollution has no influence.

*Pollution Degree 2*—Normally, only nonconductive pollution occurs. However, a temporary conductivity caused by condensation must be expected.

*Pollution Degree 3*—Conductive pollution occurs or dry nonconductive pollution occurs that becomes conductive due to condensation, which is to be expected.

*Pollution Degree 4*—Continuous conductivity occurs due to conductive dust, rain, or other wet conditions.

## Installation Category

*Overvoltage Category*—This section addresses insulation coordination by identifying the transient overvoltages that may occur and by assigning four different levels as indicated in IEC 60664.

- I: Signal Level—Special equipment or parts of equipment
- II: Local Level—Portable equipment, etc.
- III: Distribution Level—Fixed installation
- IV: Primary Supply Level—Overhead lines, cable systems

Each successive category should be subject to smaller transients than any higher-numbered category following it.

### REVISION HISTORY

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**Changes from Revision B (June 2013) to Revision C** **Page**

- Changed temperature grade from 3 to 1 ..... 1
- 

**Changes from Revision A (September 2011) to Revision B** **Page**

- Added AEC-Q100 qualifications ..... 1
  - Changed signaling-rate limit to 100 Mbps ..... 1
  - Deleted Ordering Information table ..... 3
  - Changed last sentence in the Installation Category section ..... 19
-

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ISO721QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	IS721Q	<a href="#">Samples</a>
ISO722QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 125	IS722Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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**OTHER QUALIFIED VERSIONS OF ISO721-Q1, ISO722-Q1 :**

- Catalog: [ISO721](#), [ISO722](#)

## NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO721QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO722QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ISO721QDRQ1	SOIC	D	8	2500	367.0	367.0	38.0
ISO722QDRQ1	SOIC	D	8	2500	367.0	367.0	38.0



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4211283-2/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
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Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
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### Applications

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Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
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Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
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